

Chip Termination 5 Watts, 50Ω



Features:

- 5 Watts
- Lowest Cost
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

Resistive Element	Thick film
Substrate	BeO Ceramic
Terminal Finish	Matte Tin over Nickel
Operating Temperature	-55 to +125°C (see chart)

Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

Electrical Specifications

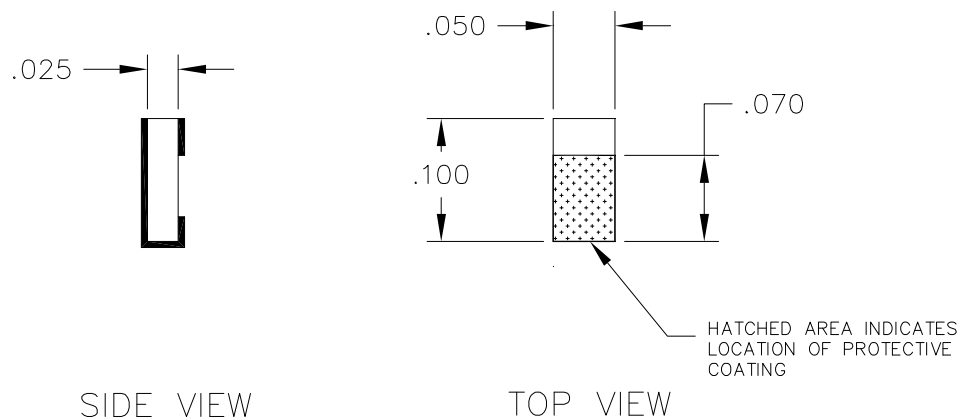
Resistance Value:	50 ohms, $\pm 2\%$
Power:	5 Watts
Frequency Range:	DC – 4.0 GHz
V.S.W.R.:	1.25:1

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance.

Tolerance is ± 0.010 inches.

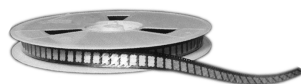
Specifications subject to change without notice

Outline Drawing

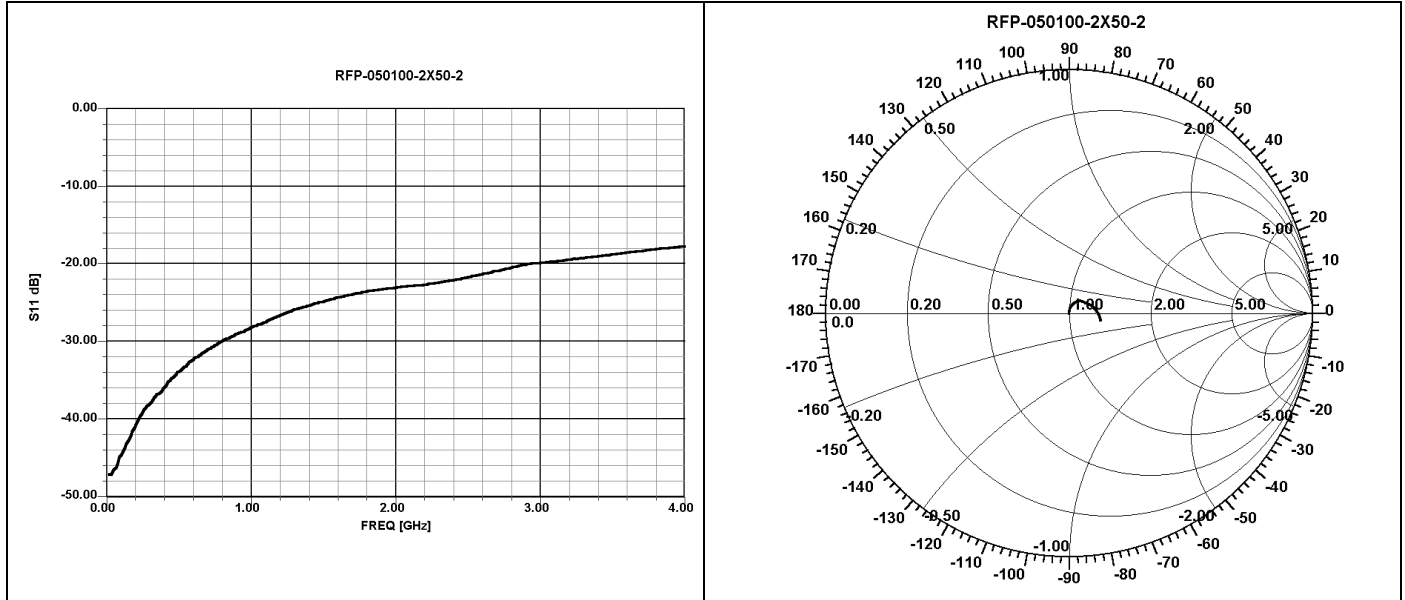


All dimensions are in inches.

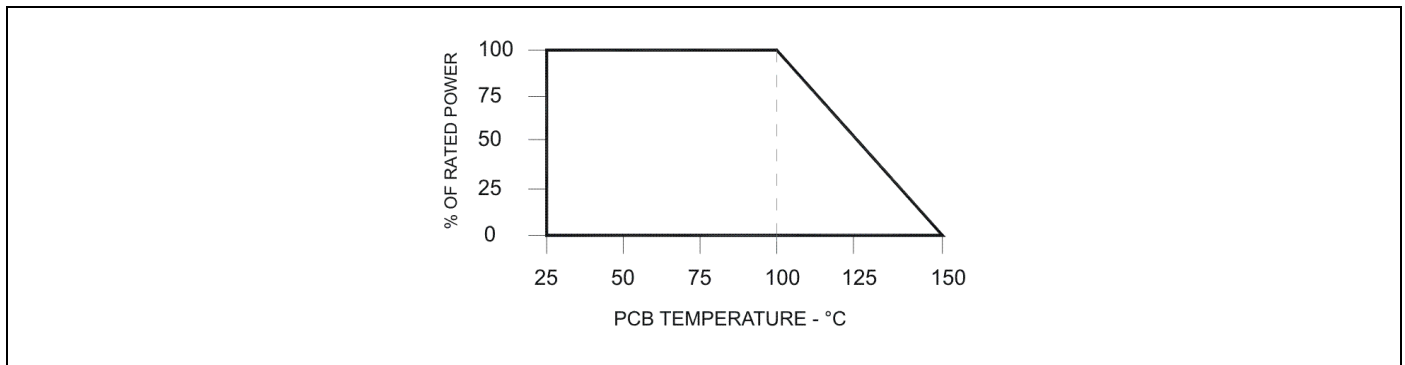
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Typical Performance:



Power De-rating:



Mounting Footprint and Procedure:

Diagram illustrating mounting footprint and procedure. The diagram shows two cross-sectional views of the device mounted on a PCB. The left view shows the device mounted on a flat surface with a lead. The right view shows the device mounted on a surface that is higher than the lead. The left view is labeled 'SUGGESTED STRESS RELIEF METHODS' and the right view is labeled 'NOT RECOMMENDED APPLICATION'.

Labels in the diagram include: .025 MIN. (2 PLACES), BOARD LOWER THAN LEAD, BOARD EVEN WITH LEAD, BOARD LOWER THAN LEAD, BOARD HIGHER THAN LEAD, SUGGESTED STRESS RELIEF METHODS, SCALE: NONE, NOT RECOMMENDED APPLICATION, SCALE: NONE.

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING SN96 SOLDER.
3. SOLDER LEADS IN PLACE USING AN SN96 TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON (260°C).

